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January 2010

FDC655BN

Single N-Channel, Logic Level, PowerTrench® MOSFET 30 V, 6.3 A, 25 m Ω

Features

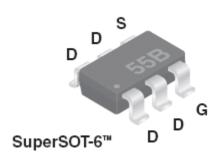
- Max $r_{DS(on)} = 25 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 6.3 \text{ A}$
- Max $r_{DS(on)} = 33 \text{ m}\Omega$ at $V_{GS} = 4.5 \text{ V}$, $I_D = 5.5 \text{ A}$
- Fast switching
- Low gate charge
- High performance trchnology for extremely low r_{DS(on)}
- Termination is Lead-free and RoHS Compliant

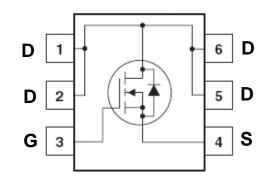
General Description

This N-Channel Logic Level MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

These devices are well suited for low voltage and battery powered applications where low in-line power loss and fast switching are required.







MOSFET Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter			Ratings	Units
V _{DS}	Drain to Source Voltage			30	V
V_{GS}	Gate to Source Voltage			±20	V
	-Continuous	T _A = 25°C	(Note 1a)	6.3	^
'D	-Pulsed			20	A
D	Power Dissipation		(Note 1a)	1.6	W
P_{D}	Power Dissipation		(Note 1b)	0.8	VV
T _J , T _{STG}	Operating and Storage Junction Temperature R	ange		-55 to + 150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	78	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
.55B	FDC655BN	SSOT-6 TM	7 "	8 mm	3000 units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	octeristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	30			V
$\frac{\Delta BV_{DS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu A$, referenced to 25°C		25		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 24 V, V _{GS} = 0 V			1	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	1	1.9	3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250 \mu A$, referenced to 25°C		-5		mV/°C
		$V_{GS} = 10 \text{ V}, I_D = 6.3 \text{ A}$		21	25	
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 5.5 \text{ A}$		26	33	mΩ
, ,		$V_{GS} = 10 \text{ V}, I_D = 6.3 \text{ A}, T_J = 125^{\circ}\text{C}$		30	36	
9 _{FS}	Forward Transconductance	$V_{DS} = 10 \text{ V}, I_{D} = 6.3 \text{ A}$		35		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 45 V V 0 V	470	620	pF
Coss	Output Capacitance	V _{DS} = 15 V, V _{GS} = 0 V, f = 1MHz	100	130	pF
C _{rss}	Reverse Transfer Capacitance	- 1101112	60	90	pF
R_g	Gate Resistance		3.0		Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time		6	11	ns
t _r	Rise Time	V _{DD} = 15 V, I _D = 1 A,	2	10	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	15	26	ns
t _f	Fall Time		2	10	ns
Q_g	Total Gate Charge	V _{GS} = 0 V to 10 V	9	13	nC
Qg	Total Gate Charge	$V_{GS} = 0 \ V \text{ to 5 } V \qquad V_{DD} = 15 \ V,$	5	7	nC
Q _{gs}	Gate to Source Charge	I _D = 6.3 A	1.4		nC
Q_{gd}	Gate to Drain "Miller" Charge		1.6		nC

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain-Source Diode Forward Current			1.3	Α
V_{SD}	Source-Drain Diode Forward Voltage $V_{GS} = 0 \text{ V}, I_S = 1.3 \text{ A}$ (Note 2)		0.8	1.2	V
t _{rr}	Reverse Recovery Time	I _E = 6.3 A, di/dt = 100 A/μs		26	ns
Q _{rr}	Reverse Recovery Charge	- 1 _F = 0.5 A, α//αt = 100 A/μs		10	nC

Notes:

- 1: R_{0,IA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{0,IC} is guaranteed by design while R_{0,CA} is determined by the user's board design.
 - a. 78 °C/W when mounted on a 1 in 2 pad of 2 oz copper on FR-4 board.
 - b. 156 °C/W when mounted on a minimum pad.
- 2: Pulse Test: Pulse Width<300 us, Duty Cycle<2.0%.

Typical Characteristics T_J = 25°C unless otherwise noted

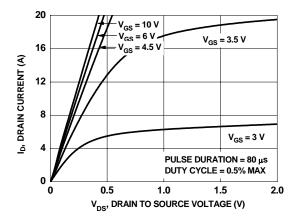


Figure 1. On Region Characteristics

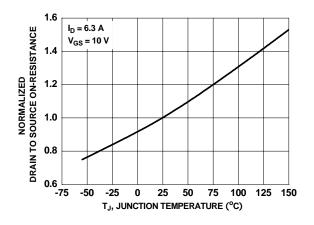


Figure 3. Normalized On Resistance vs Junction Temperature

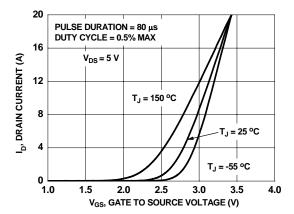


Figure 5. Transfer Characteristics

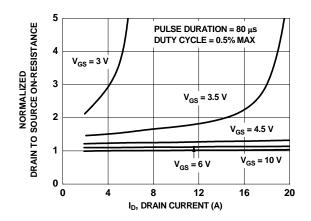


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

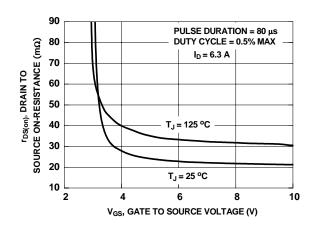


Figure 4. On-Resistance vs Gate to Source Voltage

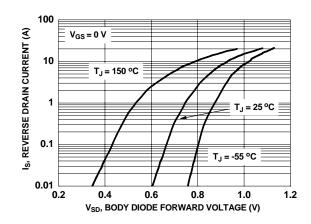


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

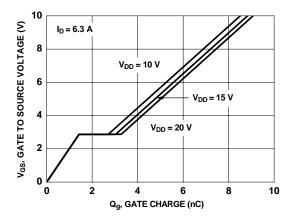


Figure 7. Gate Charge Characteristics

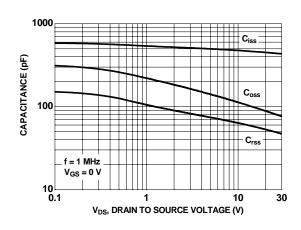


Figure 8. Capacitance vs Drain to Source Voltage

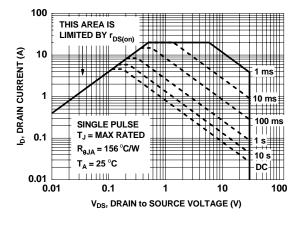


Figure 9. Forward Bias Safe Operating Area

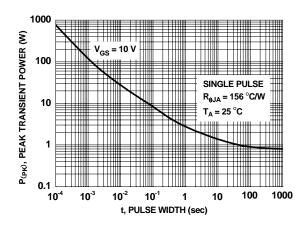


Figure 10. Single Pulse Maximum Power Dissipation

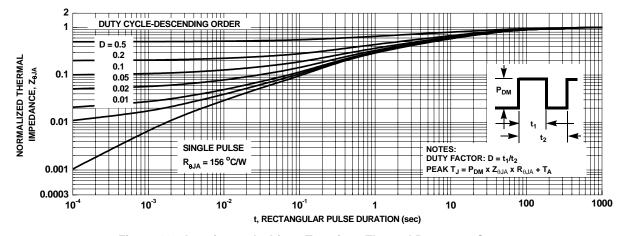


Figure 11. Junction-to-Ambient Transient Thermal Response Curve





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